



## News Release

### **Unisem (M) Berhad Holds Groundbreaking Ceremony for Its New Semiconductor Production Facility in Gopeng, Perak, Malaysia**

**Kuala Lumpur 22 March 2022** Unisem (M) Berhad ("UNISEM") held a groundbreaking ceremony this morning to commemorate the commencement of construction of its new semiconductor production facility on a piece of industrial land measuring approximately 28.5 acres in Gopeng, Perak, Malaysia ("Gopeng Plant"). Phase 1 of this new Gopeng Plant with an aggregate built up area of about 57,000 square meters with cleanroom facilities, is expected to be completed in April 2023 at an approximate cost of RM300 million. Once completed, fully facilitated and equipped with the latest state-of-the-art equipment, the Gopeng Plant will enable UNISEM to better serve the needs of our customers with a broad portfolio of products and services. It will also enable UNISEM to double the production capacity of UNISEM's existing operations in Ipoh.

UNISEM first established its semiconductor production facility in Simpang Pulai, Ipoh, Perak and commenced production in 1992. Over the years, UNISEM has fully utilised the 15-acre piece of land with a total built-up area of about 570,000 square feet and has 3,500 employees currently.

Commenting on another milestone in the history of UNISEM, Mr John Chia Sin Tet, Chairman/Group Managing Director of UNISEM said "The building of this flagship facility at Gopeng reflects the view of the Board that Malaysia remains an important destination in the global semiconductor supply chain. The Gopeng Plant will further create more high value job opportunities for Malaysians whilst contributing to the country's exports.

We wish to thank the Perak state government, MIDA and all the local authorities for their support, encouragement and granting us the necessary approvals for the construction of our flagship facility in Perak."

The ceremony was attended by the Board of Directors and senior management of UNISEM. The representatives of the General Contractor, Zalam Corporation Sdn Bhd and other nominated sub-contractors were also in attendance.

#### **About Unisem**

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has production facilities locations in Ipoh, Malaysia and in Chengdu, China. Unisem is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at [www.unisemgroup.com](http://www.unisemgroup.com) or email us at [investor@unisemgroup.com](mailto:investor@unisemgroup.com)